

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	562596	(flip adj chip or BGA or (ball adj grid) or IC or device or package or die or dice or dies) near8 (board or substrate or wafer or PCB or (print adj circuit adj board) or MCM or multi-chip or (multi adj chip) or interposer or leadframe or (lead adj frame))	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/07/15 12:50
2	BRS	L2	3146919	(diisocyanate adj monomers) or (diisocynate adj end-capped adj compliant adj oligomer) or (ptoluenesulfonyl adj semicarbazide) or (hydroxyl adj end-capped adj oligomer) or (carboxylic adj acid adj polymer) or water or "H.sub.2O" or (polymer\$6 near2 foam\$6)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/07/15 12:39
3	BRS	L3	57566	((diisocyanate adj monomers) or (diisocynate adj end-capped adj compliant adj oligomer) or (ptoluenesulfonyl adj semicarbazide) or (hydroxyl adj end-capped adj oligomer) or (carboxylic adj acid adj polymer) or water or "H.sub.2O" or (polymer\$6 near2 foam\$6)) near4 (filling or filler or infill or insulat\$4)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/07/15 12:39

	Type	L #	Hits	Search Text	DBs	Time Stamp
4	BRS	L4	1561	((diisocyanate adj monomers) or (diisocynate adj end-capped adj compliant adj oligomer) or (ptoluenesulfonyl adj semicarbazide) or (hydroxyl adj end-capped adj oligomer) or (carboxylic adj acid adj polymer) or water or "H.sub.2O" or (polymer\$6 near2 foam\$6)) near4 (filling or filler or infill or insulat\$4)) and ((flip adj chip or BGA or (ball adj grid) or IC or device or package or die or dice or dies) near8 (board or substrate or wafer or PCB or (print adj circuit adj board) or MCM or multi-chip or (multi adj chip) or interposer or leadframe or (lead adj frame)))	USPAT; US-PGP; UB; EPO; JPO; DERWENT; IBM_TD	2004/07/15 12:39
5	BRS	L6	3144546	(diisocyanate adj monomers) or (diisocynate adj end-capped adj compliant adj oligomer) or (ptoluenesulfonyl adj semicarbazide) or (hydroxyl adj end-capped adj oligomer) or (carboxylic adj acid adj polymer) or water or (polymer\$6 near2 foam\$6)	USPAT; US-PGP; UB; EPO; JPO; DERWENT; IBM_TD	2004/07/15 12:39
6	BRS	L7	107185	((diisocyanate adj monomers) or (diisocynate adj end-capped adj compliant adj oligomer) or (ptoluenesulfonyl adj semicarbazide) or (hydroxyl adj end-capped adj oligomer) or (carboxylic adj acid adj polymer) or water or (polymer\$6 near2 foam\$6)) near4 (filling or filler or infill or insulat\$4 or support\$4)	USPAT; US-PGP; UB; EPO; JPO; DERWENT; IBM_TD	2004/07/15 12:40

	Type	L #	Hits	Search Text	DBs	Time Stamp
7	BRS	L5	151	((diisocyanate adj monomers) or (diisocynate adj end-capped adj compliant adj oligomer) or (ptoluenesulfonyl adj semicarbazide) or (hydroxyl adj end-capped adj oligomer) or (carboxylic adj acid adj polymer) or water or "H.sub.20" or (polymer\$6 near2 foam\$6)) near4 (filling or filler or infill or insulat\$4)) same ((flip adj chip or BGA or (ball adj grid) or IC or device or package or die or dice or dies) near8 (board or substrate or wafer or PCB or (print adj circuit adj board) or MCM or multi-chip or (multi adj chip) or interposer or leadframe or (lead adj frame)))	USPAT; US-PGP; UB; EPO; JPO; DERWENT; IBM_TD; B	2004/07/15 12:40
8	BRS	L8	282	((diisocyanate adj monomers) or (diisocynate adj end-capped adj compliant adj oligomer) or (ptoluenesulfonyl adj semicarbazide) or (hydroxyl adj end-capped adj oligomer) or (carboxylic adj acid adj polymer) or water or (polymer\$6 near2 foam\$6)) near4 (filling or filler or infill or insulat\$4 or support\$4)) same ((flip adj chip or BGA or (ball adj grid) or IC or device or package or die or dice or dies) near8 (board or substrate or wafer or PCB or (print adj circuit adj board) or MCM or multi-chip or (multi adj chip) or interposer or leadframe or (lead adj frame)))	USPAT; US-PGP; UB; EPO; JPO; DERWENT; IBM_TD; B	2004/07/15 12:40

	Type	L #	Hits	Search Text	DBs	Time Stamp
9	BRS	L9	773475	interconnect\$6 or inter-connect\$6	USPAT; US - PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/07/15 12:41
10	BRS	L10	49337	(expose\$4 or top or surface) near4 9	USPAT; US - PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/07/15 12:42
11	BRS	L11	238789 3	reaction or react\$6 or polymerization	USPAT; US - PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/07/15 12:42
12	BRS	L12	199276 4	substrate or wafer	USPAT; US - PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/07/15 12:42
13	BRS	L15	27453	polymer\$4 near2 (foam\$6 or bubbles or spray\$6)	USPAT; US - PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/07/15 12:48

	Type	L #	Hits	Search Text	DBs	Time Stamp
14	BRS	L16	4	14 and 15	USPAT; US - PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/07/15 12:48
15	BRS	L14	481	10 same 11 same 12	USPAT; US - PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/07/15 12:49
16	BRS	L18	287	14 and 1	USPAT; US - PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/07/15 12:50

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L3	287	((expose\$4 or top or surface) near4 (interconnect\$6 or inter-connect\$6)) same (reaction or react\$6 or polymerization) same (substrate or wafer)) and ((flip adj chip or BGA or (ball adj grid) or IC or device or package or die or dice or dies) near8 (board or substrate or wafer or PCB or (print adj circuit adj board) or MCM or multi-chip or (multi adj chip) or interposer or leadframe or (lead adj frame)))	USPAT; US-PGP UB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 16:39
2	BRS	L4	27453	polymer\$4 near2 (foam\$6 or bubbles or spray\$6)	USPAT; US-PGP UB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 17:36
3	BRS	L5	49337	(expose\$4 or top or surface) near4 (interconnect\$6 or inter-connect\$6)	USPAT; US-PGP UB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 16:40
4	BRS	L6	275	4 and 5	USPAT; US-PGP UB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 17:36

	Type	L #	Hits	Search Text	DBs	Time Stamp
5	BRS	L7	21684	polymer\$4 near2 foam\$6	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/07/15 17:36
6	BRS	L8	476	7 near4 (substrates or wafers)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/07/15 17:38
7	BRS	L9	16	8 same interconnect\$6	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/07/15 17:37
8	BRS	L10	16	8 same (inject\$6 or spray\$6 or diffus\$6 or immers\$6)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/07/15 18:00
9	BRS	L13	555	7 same interconnect\$6	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/07/15 18:02

	Type	L #	Hits	Search Text	DBs	Time Stamp
10	BRS	L14	223	13 and (substrate or wafer)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/07/15 18:29
11	IS&R	L18	455	(438/782) .CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/07/15 18:29
12	BRS	L19	2264	15 or 16 or 17 or 18	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/07/15 18:29
13	BRS	L20	7	19 and 7	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/07/15 18:29
14	IS&R	L21	354	(438/762) .CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/07/15 18:32

	Type	L #	Hits	Search Text	DBs	Time Stamp
15	IS&R	L22	134	(438/765) .CCLS.	USPAT; US - PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/07/15 19:13
16	IS&R	L23	1448	(438/780) .CCLS.	USPAT; US - PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/07/15 19:46